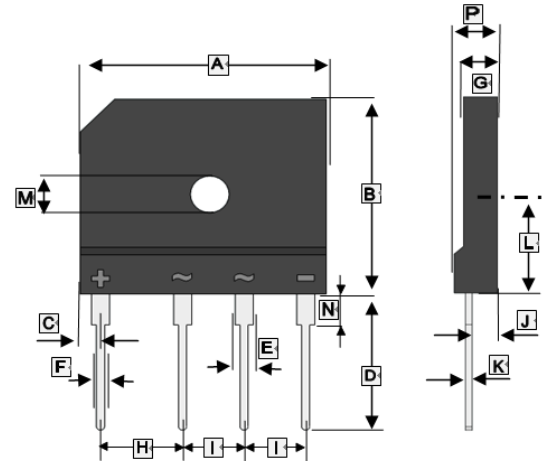


RoHS Compliant Product

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- Plastic material has Underwriters Laboratory flammability classification 94V-0
- Mounting position: Any
- These are Halogen & Pb Free components
- This series is UL recognized under Component Index, file number E255340

GBJ



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	29.7	30.3	I	7.3	7.7
B	19.7	20.3	J	2.5	2.9
C	2.3	2.7	K	0.6	0.8
D	17	18	L	10.8	11.2
E	2.0	2.4	M	φ 3.1	φ 3.4
F	0.9	1.1	N	3.8	4.2
G	3.4	3.8	P	4.4	4.8
H	9.8	10.2			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter	Symbo	Part Number				Unit
		S20GBJ20-C	S20GBJ40-C	S20GBJ60-C	S20GBJ80-C	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	V
Average Rectified Output Current @50HZ sine wave, R-load	$T_C=110^\circ\text{C}$ (with heat sink)	20				A
	$T_A=25^\circ\text{C}$ (without heat sink)	3.5				
Peak Forward Surge Current @ 50Hz sine wave, 1 cycle, $T_A=25^\circ\text{C}$	I_{FSM}	240				A
Maximum Peak Forward Voltage ³	V_{FM}	1.1				V
Peak Reverse Current ²	I_{RRM}	10				μA
I^2t Rating for Fusing @1ms≤t<8.3ms, $T_J=25^\circ\text{C}$, Rating of per diode	I^2t	239				A ² s
Mounting Torque @ Recommend	TOR	8				Kg · cm
Dielectric Strength ¹	Vdis	2.5				kV
Typical Thermal Resistance (with heat sink)	$R_{\theta JC}$	1.5				°C/W
Typical Thermal Resistance(without heat sink)	$R_{\theta JA}$	22				°C/W
Typical Thermal Resistance(without heat sink)	$R_{\theta JL}$	5				°C/W
Operating and Storage temperature range	T_J, T_{STG}	150, -40~150				°C

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=10\text{A}$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

